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**Amendments to the Claims:**

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A material arranging method of arranging a material on a base, the method comprising:

~~an ejection step of~~ ejecting the material from at least one nozzle toward a predetermined area of the base, which is provided in a vacuum atmosphere that is adjusted to a high degree of vacuum; and

~~a detection step of~~ detecting an ejection failure of a nozzle in the vacuum atmosphere before starting the ejection step.

2. (Currently Amended) A material arranging method of arranging a material on a base, the method comprising:

~~an ejection step of~~ ejecting the material from at least one nozzle toward a predetermined area of the base, which is provided in a vacuum atmosphere that is adjusted to a pressure of  $10^{-3}$  torr or less; and

~~a detection step of~~ detecting an ejection failure of a nozzle in the vacuum atmosphere before starting the ejection step.

3. (Currently Amended) A material arranging method of arranging a material on a base, the method comprising:

~~an ejection step of~~ ejecting the material from at least one nozzle toward a predetermined area of the base, which is provided in a vacuum atmosphere that is adjusted to a pressure of  $10^{-5}$  torr or less; and

~~a detection step of~~ detecting an ejection failure of a nozzle in the vacuum atmosphere before starting the ejection step.

4. (Currently Amended) The material arranging method according to Claim 1, ~~wherein the detection step includes~~ detecting an ejection failure further including an action of ejecting the material to a preliminary-ejecting area other than the predetermined area and detecting the ejection failure of a nozzle on the basis of the ejecting result.

5. (Currently Amended) The material arranging method according to Claim 1, ~~wherein the detection step includes~~ detecting an ejection failure further including an action of providing a preliminary member in the predetermined area, ejecting the material to a

preliminary-ejecting area provided in the preliminary member, and detecting the ejection failure of a nozzle on the basis of the ejection result.

6. (Currently Amended) ~~A~~The material arranging method according to Claim 4,  
~~wherein the detection of the ejection failure~~detecting an ejection failure of a nozzle ~~is~~being  
performed by detecting ~~the~~a light-reflectivity of the material ejected to the preliminary-  
ejecting area.

7. (Currently Amended) The material arranging method according to Claim 4,  
~~wherein the detection of the ejection failure~~detecting the ejection failure of the at least one  
nozzle ~~is~~being performed by detecting ~~the~~a light-transmissivity of the material ejected to the  
preliminary-ejecting area.

8. (Currently Amended) The material arranging method according to Claim 1,  
~~wherein the detection step is~~detecting the ejection failure being performed at the time of  
changing of the material in the ejection step.

9. (Currently Amended) A material arranging method of arranging a material on  
a base, the method comprising:

~~an ejection step of~~ ejecting the material from at least one nozzle toward a  
predetermined area of the base, which is provided in a vacuum atmosphere that is adjusted to  
a high degree of vacuum; and

~~a preliminary ejection step of~~ preliminarily ejecting the material from a nozzle  
toward an area on the base other than the predetermined area before starting the ejection step.

10. (Currently Amended) A material arranging method of arranging a material on  
a base, the method comprising:

~~an ejection step of~~ ejecting the material from at least one nozzle toward a  
predetermined area of the base, which is provided in a vacuum atmosphere that is adjusted to  
a pressure of  $10^{-3}$  torr or less; and

~~a preliminary ejection step of~~ preliminarily ejecting the material from a nozzle  
toward an area on the base other than the predetermined area before starting the ejection step.

11. (Currently Amended) A material arranging method of arranging a material on  
a base, the method comprising:

~~an ejection step of~~ ejecting the material from at least one nozzle toward a  
predetermined area of the base, which is provided in a vacuum atmosphere that is adjusted to  
a pressure of  $10^{-5}$  torr or less; and

~~a preliminary ejection step of~~ preliminarily ejecting the material from a nozzle toward an area on the base other than the predetermined area, before starting the ejection step.

12. (Currently Amended) ~~A~~The material arranging method according to Claim 9, ~~wherein the preliminary ejection step performs~~performing the preliminary ejection of the nozzle in a process immediately previous to the ejection step.

13. (Currently Amended) ~~A~~The material arranging method according to Claim 9, ~~wherein the preliminary ejection step is~~being performed at the time of changing the material in the ejection step.

14. (Currently Amended) The material arranging method according to Claim 9, further comprising a ~~positional correction step of~~ detecting an arranged position of the material arranged through the preliminary ejection and a target position to arrange the material through the preliminary ejection right after the preliminary ejection step, and performing a positional correction of a nozzle when a positional deviation occurs between the arranged position and the target position.

15. (Currently Amended) A method of manufacturing an electronic device, ~~wherein at least some elements constituting the electronic device are~~being formed using the material arranging method according to Claim 1.

16. (Currently Amended) The method of manufacturing an electronic device according to Claim 15, ~~wherein a material for forming at least one of a conductive layer, a semiconductor layer, and an insulating layer constituting a transistor or a memory element is~~being arranged as the material, and then the conductive layer, the semiconductor layer, or the insulating layer is formed.

17. (Currently Amended) The method of manufacturing an electronic device according to Claim 15, ~~wherein patterns for separating that separate~~ wires from each other ~~are~~being formed in advance on the base, the forming material ~~is~~being arranged in the patterns, and then the conductive layer ~~is~~being formed.

18. (Currently Amended) A method of manufacturing an electro-optical device, ~~wherein at least some elements constituting the electro-optical device are~~being formed using the material arranging method according to Claim 1.

19. (Currently Amended) The method of manufacturing an electro-optical device according to Claim 18, ~~wherein a material for forming that forms~~ at least one of an electron-transporting layer, a hole-transporting layer, a light-emitting layer, and electrodes constituting an organic electroluminescent element ~~is~~being arranged as the material, and then the electron-

transporting layer, the hole-transporting layer, the light-emitting layer, or the electrodes is being formed.

20. (Currently Amended) The method of manufacturing an electro-optical device according to Claim 18, ~~wherein~~ partitions for separating that separate pixels from each other ~~are~~ being formed in advance on the base, the forming material ~~is~~ being arranged in the partitions, and then the electron-transporting layer, the hole-transporting layer, or the light-emitting layer ~~is~~ being formed.

21. (Currently Amended) A film-forming apparatus comprising:  
a processing chamber;  
a pressure control system ~~for controlling the~~ that controls a pressure in the processing chamber to a low pressure;  
at least one nozzle provided in the processing chamber and connected to a material supply source, ~~for arranging that~~ arrange a material on a member provided in the processing chamber;  
a stage provided in the processing chamber ~~for holding the~~ that holds a member;  
a moving means for relatively moving the device that relatively move a position of the nozzle or the stage; and  
an inspecting means device for inspecting that inspects the material arranged on the member.

22. (Currently Amended) A film-forming apparatus comprising:  
a processing chamber;  
a pressure control system ~~for controlling the~~ that controls a pressure in the processing chamber to a low pressure;  
a head having a plurality of nozzles provided in the processing chamber and connected to a material supply source, ~~for arranging that~~ arrange a material on a member provided in the processing chamber;  
a stage provided in the processing chamber ~~for holding that~~ holds the member;  
a moving means for relatively moving the device that relatively moves a position of the nozzles or the stage; and  
an inspecting means for inspecting device that inspects the material arranged on the member.

23. (Currently Amended) The film-forming apparatus according to Claim 21, ~~wherein~~ the member ~~is~~being a base having a predetermined area in which a film of the material is formed.

24. (Currently Amended) The film-forming apparatus according to Claim 21, ~~wherein~~ the member ~~is~~being a preliminary member having a preliminary-ejecting area.

25. (Currently Amended) The film-forming apparatus according to Claim 21, ~~wherein~~ the nozzles further ~~comprise~~including a preliminary nozzle to be used in place of a nozzle having an ejection failure, when the ejection failure occurs in one of the nozzles.

26. (Currently Amended) The film-forming apparatus according to Claim 21, ~~wherein~~ the inspecting ~~means comprises~~device including a detecting ~~means for~~detecting device for detecting an ejection failure of the nozzles on the basis of an ejecting result of the material.

27. (Currently Amended) The film-forming apparatus according to Claim 21, ~~wherein~~ the inspecting ~~means~~device further ~~comprises~~comprising a position correcting ~~means for detecting device that detects~~ an arranged position of the material and a target position to arrange the material and performing a positional correction of the nozzles when a positional deviation occurs between the arranged position and the target position.

28. (Original) An electronic device manufactured using the film-forming apparatus according to Claim 21.

29. (Original) An electro-optical device manufactured using the film-forming apparatus according to Claim 21.

30. (Currently Amended) An electronic apparatus comprising the electro-optical device according to Claim 29 as a display ~~means~~device.